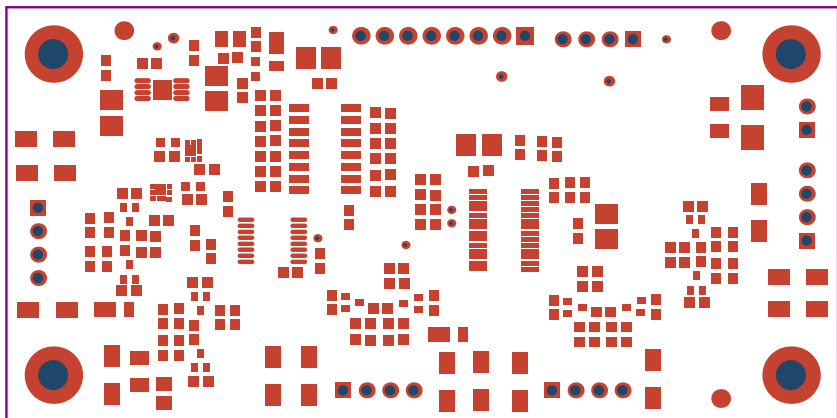
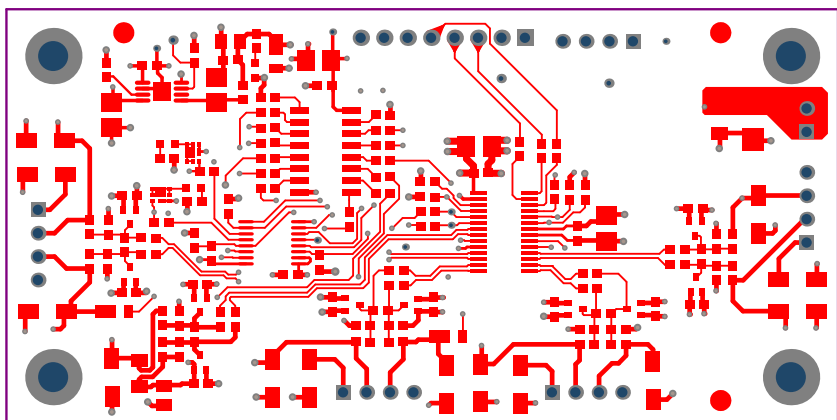


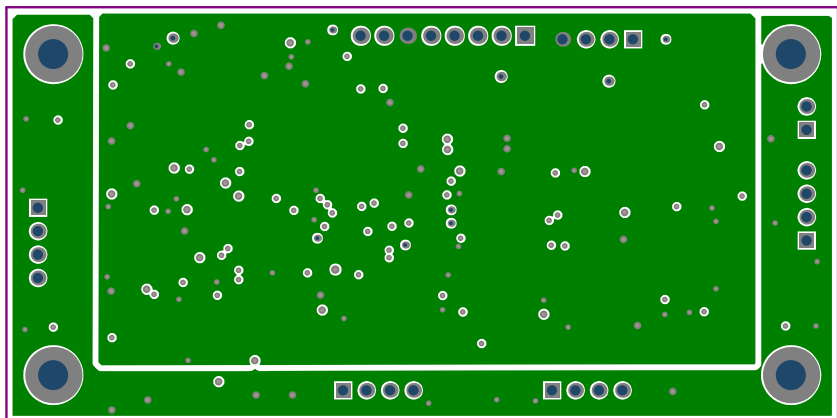
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



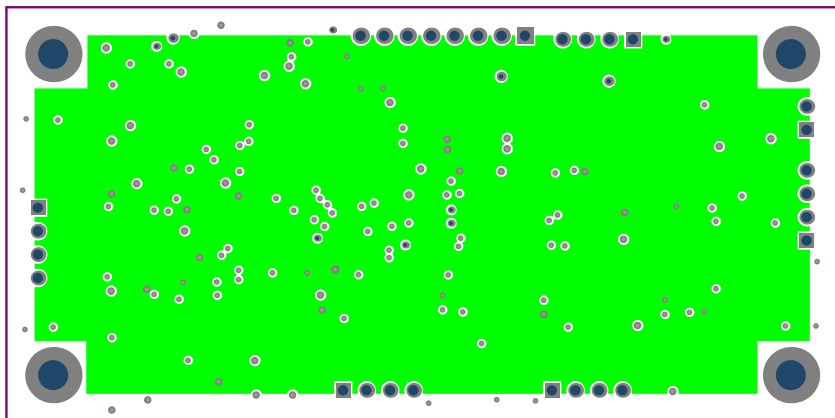
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



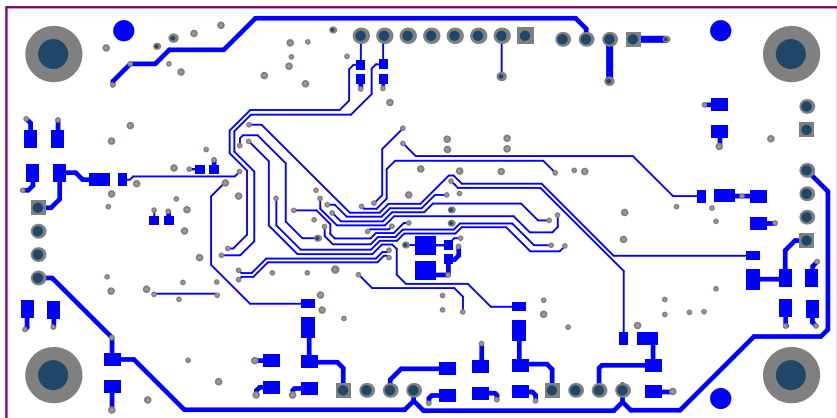
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



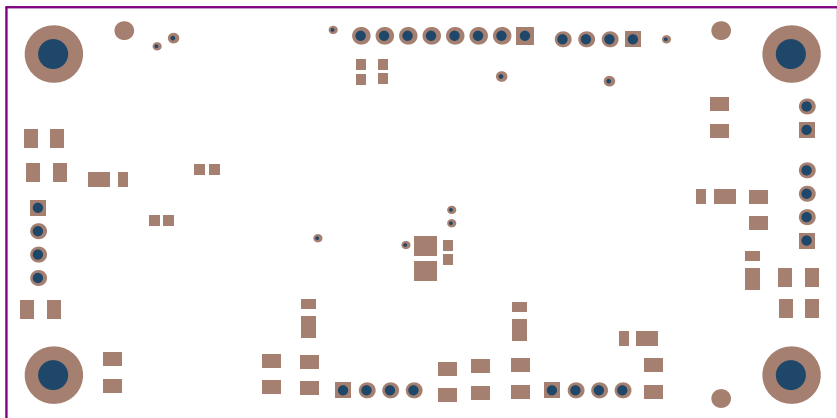
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = L2_GND-PLANE			
PLOT NAME = P1_GNDPLANE	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



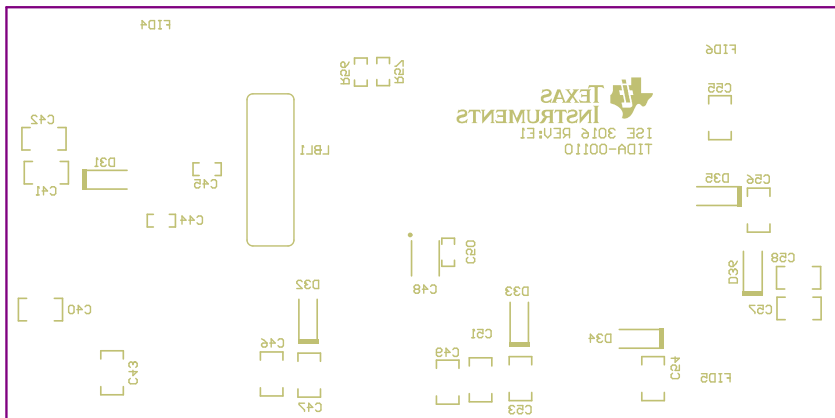
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = L3_PWR-PLANE			
PLOT NAME = P2_PWRPLANE	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



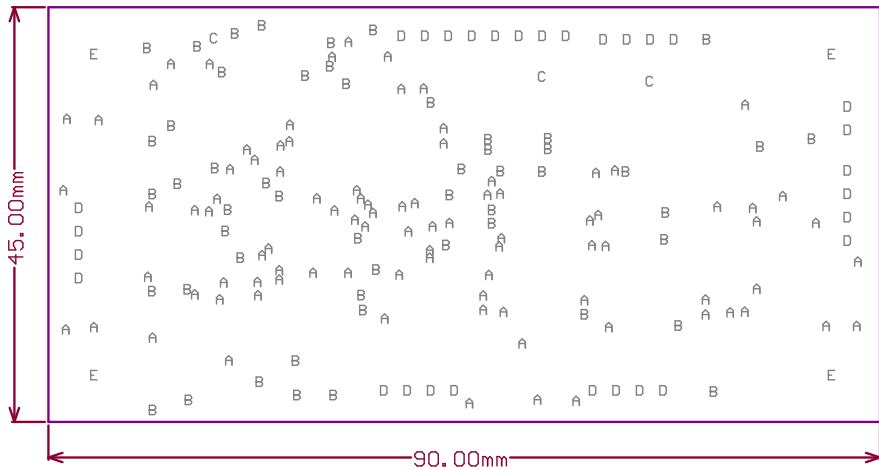
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
A	92	12mil (0.305mm)	PTH	Round
B	53	16mil (0.406mm)	PTH	Round
C	3	20mil (0.508mm)	PTH	Round
D	30	43.307mil (1.1mm)	PTH	Round
E	4	128mil (3.251mm)	PTH	Round
182 Total				

DRILL TOLARENCE

FOR PTH +/-3
 FOR 12MIL DRILL +0/-12MIL
 FOR 16MIL DRILL +0/-16MIL
 THIS IS NOT AN IMPEDENCE CONTROLLED BOARD

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00110	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = outline			
PLOT NAME = Board Outline	GENERATED : 10/8/2014 3:08:11 PM	TEXAS INSTRUMENTS	

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